

LCOS Backplane Process

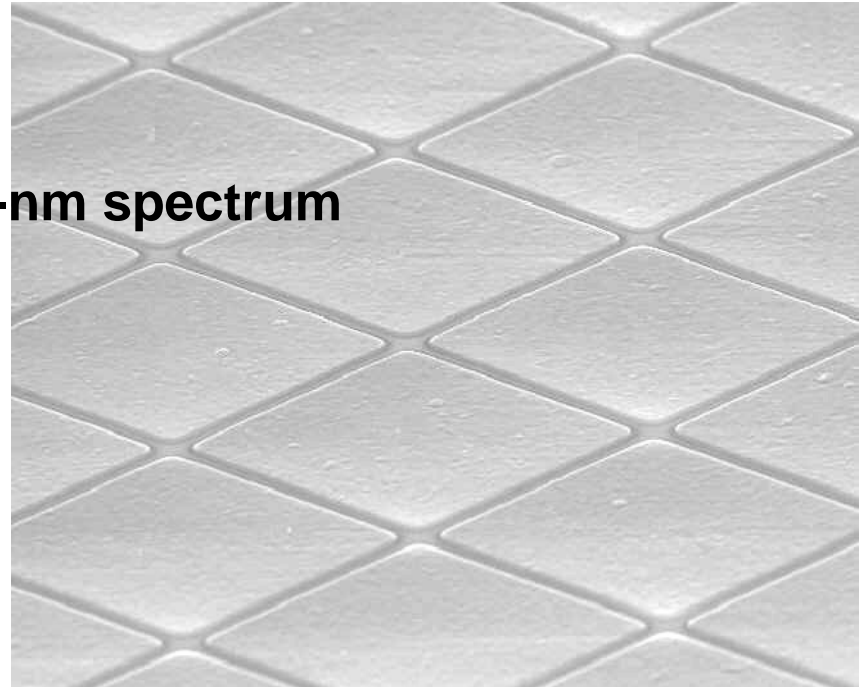
Process Technology Features

FEOL : 2.5V, 3.3V, 5.0V

- **Options : High Voltage Process (12V, 18V etc),
Mixed-Signal Process
(Diffusion Resistor, Poly-Bulk Capacitor, etc)**

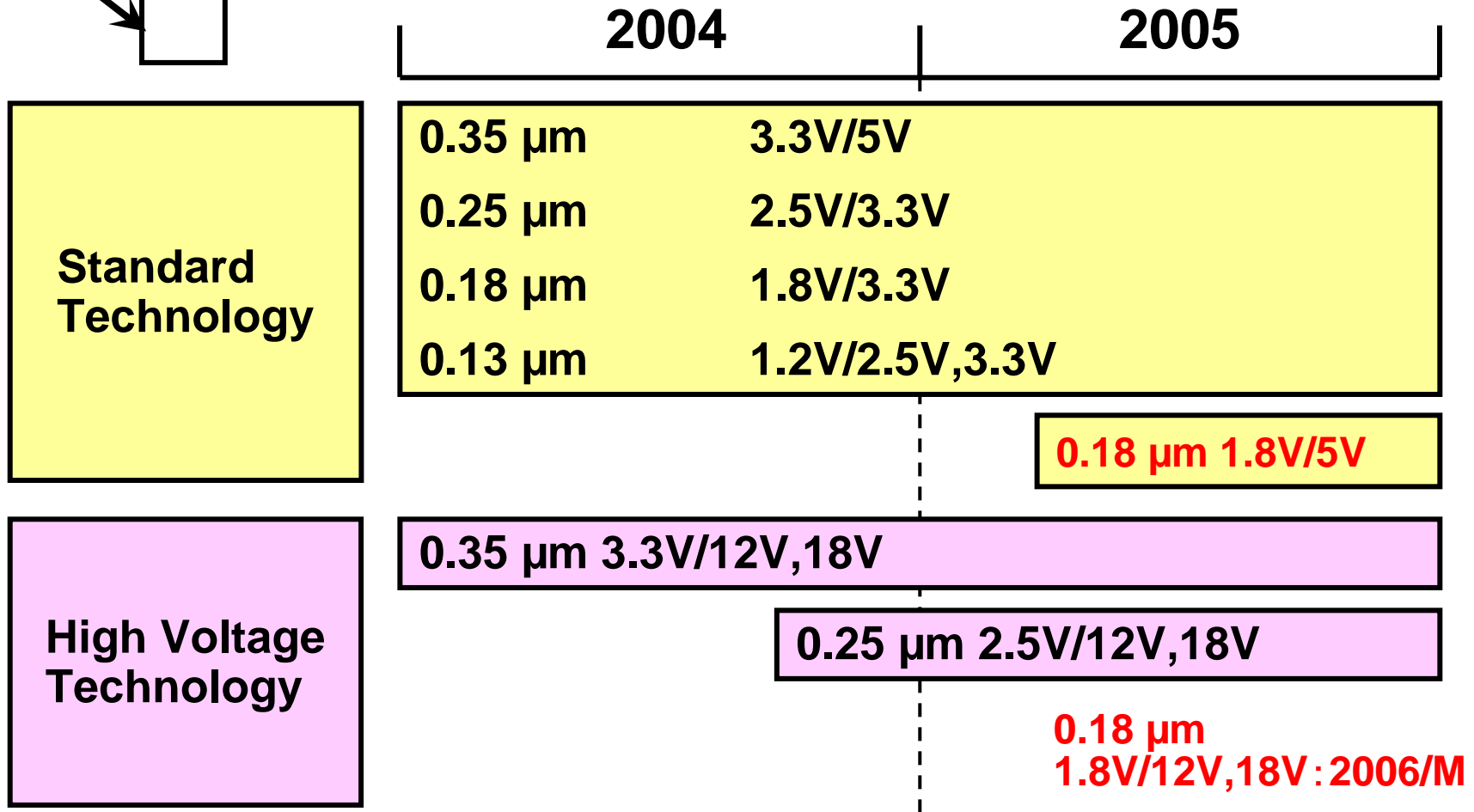
BEOL : 0.35 μ m, 0.25 μ m Metal Process

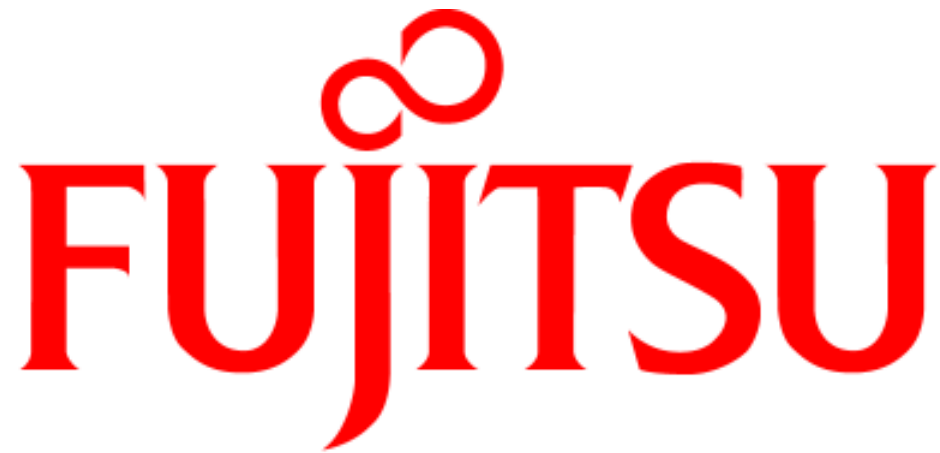
- **Panelized top metal layer**
- **Pixel-gap fills**
- **High reflectivity from 400 to 700-nm spectrum**
- **Narrow pixel space**
- **Anti-reflection layer**
- **Integrated spacer**



HV Technology Roadmap

Tape out Available





FUJITSU

THE POSSIBILITIES ARE INFINITE